

Press Release

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Rigaku Corporation and DYG Holdings LTD Announce Rigaku to Acquire XwinSys Technologies Development Ltd (XWS)

July 15th, 2019, Tokyo Japan – X-ray analytical instrument manufacturer <u>Rigaku Corporation</u> and DYG Holdings LTD today announced the closing of the acquisition process by Rigaku, a privately held scientific instrumentation company headquartered in Tokyo, as of July 1st 2019, to acquire <u>XwinSys Technology</u> <u>Development Ltd</u>, headquartered in Migdal Haemek, Israel.



Hikaru Shimura, Rigaku's President and CEO, with Doron Reinis, CEO of XwinSys Technologies Development LTD - Tokyo July 1st, 2019

XwinSys is dedicated to designing, manufacturing and marketing innovative metrology solutions based on enhanced X-ray technology, combined with automated optical 3D and 2D technologies, for the semiconductor and related industries. New industrial solutions will be developed using both Rigaku technologies, including in-line X-ray semiconductor metrology with microfocus mirror optics, and XwinSys technologies.



"The acquisition of XwinSys Technologies Development Ltd., with its unique hybrid technology, represents a significant step in the expansion of our semiconductor division," said Hikaru Shimura, Rigaku President and CEO. "By combining the existing product lines for the semiconductor industry and other state of the art technologies from Rigaku together with XwinSys Technology products and technologies, we will be able to rapidly increase our ability to act both in the semiconductor front end and back end markets."

"XwinSys and Rigaku intend to jointly develop new in-line X-ray metrology equipment for semiconductor front end and back end processes, MEMS, electronics devices and packaging, and other applications using unique technologies from both companies," said Dr. Kiyoshi Ogata, Executive Vice President & General Manager, X-ray Instrument Division and Semiconductor Metrology Division - Rigaku Corporation. "By implementing new technologies developed by Rigaku for the XwinSys system, we will be able to present to the market a new system by the end of December 2019."

"The acquisition of XwinSys by Rigaku is an ideal situation where both companies have unique, complementary technologies to enable the creation of new machines supporting multiple applications in the semiconductors market," said Doron Reinis, founder and CEO of XwinSys Technologies Development Ltd. "We intend to take full advantage of the great cooperation we get from Rigaku to support the enhancement of the semiconductor business of Rigaku Corporation."

Products from XwinSys, along with newly developed products, will be sold and supported worldwide by Rigaku Corporation's sales, service and application support organizations. XwinSys will support semiconductor customers of Rigaku products in Israel. The first joint products will be micro X-ray fluorescence (XRF) systems, which will be released by the end of December 2019.

About Rigaku Corporation

Since its inception in 1951, Rigaku has been at the forefront of analytical and industrial instrumentation technology. Today, with hundreds of major innovations to their credit, the Rigaku Group of Companies are world leaders in the fields of general X-ray diffraction (XRD), thin film analysis (XRF, XRD and XRR), X-ray fluorescence spectrometry (TXRF, EDXRF and WDXRF), small angle X-ray scattering (SAXS), protein and small molecule X-ray crystallography, Raman spectroscopy, X-ray optics, semiconductor metrology (TXRF, XRF, XRD and XRR), X-ray sources, computed tomography, nondestructive testing and thermal analysis.

With Rigaku's vast understanding of X-ray and its complementary technologies as a foundation, our true strength is seen in an unparalleled willingness to collaborate with customers. By promoting partnerships, dialog, and innovation within the global scientific and industrial communities, Rigaku demonstrates a relentless commitment to providing our client markets with fully integrated solutions.

The company and its employees are dedicated to developing and supplying universities, industry, and government labs with the ultimate in customer-focused integrated solutions across a wide variety of



disciplines, including structural proteomics, nanoengineering research, general purpose X-ray diffraction (XRD) and spectroscopy (XRF), materials analysis and quality assurance.

Whether supplying the tools to create better semiconductor chips, enabling drug discovery, improving production line quality, or exploring the new frontier of nanotechnology, Rigaku products and services lead with innovation.

Rigaku employs over 1,400 people worldwide in operations based in Japan, the U.S., Europe and China. We value our people. Our value comes from them. Close collaboration between our users and employees sets the direction and focus of our work, allowing us to address customers' needs and stay close to the market place. Information about Rigaku is available at www.rigaku.com.

About DYG Holdings LTD.

DYG Holding is a holding company formed by Doron Reinis and Yoav Allon at Sep. 2019 after successful management buyout from Eurocontrol Technics. DYG portfolio includes XwinSys, Xenemetrix (EDXRF equipment manufacturer) and Croptimal that deals with precision agriculture using multiple spectroscopy technologies. DYG Holdings is led by a team of senior managers, board members and global advisers having a vast set of experience.

About XwinSys Technologies Development Ltd.

XwinSys is dedicated to designing, manufacturing and marketing novel metrology solutions based on enhanced X-Ray technology combined with automated optical 3D and 2D technologies, for the semiconductor and related industries. XwinSys Technology Development Ltd. founded in 2012 headquartered in the hi-tech industrial park at Migdal Haemek in the northern part of Israel. The XwinSys product line offers an innovative technological solution for the rapidly growing semiconductor market. XwinSys' modular technology concept allows multiple application capabilities, cost-effective maintenance and a budget-oriented approach. The XwinSys integrated and improved X-Ray and optical (3D and 2D) analysis provides a new approach to meet the challenges of roadmap requirements for inspection and metrology of 3D structures, thin-films, multi-stack and organic applications of the semiconductor industry. Information about XwinSys is available at www.xwinsys.com.

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